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September 2014

# FDS4465

# P-Channel 1.8V Specified PowerTrench® MOSFET

#### **General Description**

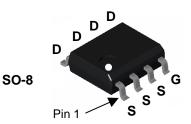
This P-Channel 1.8V specified MOSFET is a rugged gate version of Fairchild Semiconductor's advanced PowerTrench process. It has been optimized for power management applications with a wide range of gate drive voltage (1.8V-8V).

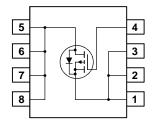
### **Applications**

- Power management
- Load switch
- · Battery protection

#### **Features**

- -13.5 A, -20 V. 
  $$\begin{split} R_{DS(ON)} = 8.5 & \, m\Omega \,\, @ \,\, V_{GS} = -4.5 \,\, V \\ R_{DS(ON)} = 10.5 & \, m\Omega \,\, @ \,\, V_{GS} = -2.5 \,\, V \\ R_{DS(ON)} = 14 & \, m\Omega \,\, @ \,\, V_{GS} = -1.8 \,\, V \end{split}$$
- · Fast switching speed
- High performance trench technology for extremely low  $R_{\text{DS}(\text{ON})}$
- · High current and power handling capability





#### Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

| Symbol                            | Parameter  |           | Ratings     | Units |
|-----------------------------------|--|-----------|-------------|-------|
| V <sub>DSS</sub>                  | Drain-Source Voltage                             |           | -20         | V     |
| V <sub>GSS</sub>                  | Gate-Source Voltage                              |           | ±8          | V     |
| I <sub>D</sub>                    | Drain Current - Continuous                       | (Note 1a) | -13.5       | Α     |
|                                   | - Pulsed   |           | -50         |       |
| P <sub>D</sub>                    | Power Dissipation for Single Operation           | (Note 1a) | 2.5         | W     |
|                                   |  | (Note 1b) | 1.5         |       |
|                                   |  | (Note 1c) | 1.2         |       |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Junction Temperature Range |           | −55 to +175 | °C    |

#### **Thermal Characteristics**

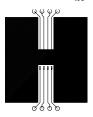
| $R_{\theta JA}$  | Thermal Resistance, Junction-to-Ambient | (Note 1a) | 50  | °C/W |
|------------------|---|-----------|-----|------|
| $R_{\theta JA}$  | Thermal Resistance, Junction-to-Ambient | (Note 1c) | 125 | °C/W |
| R <sub>θJC</sub> | Thermal Resistance, Junction-to-Case    | (Note 1)  | 25  | °C/W |

Package Marking and Ordering Information

|          |        | <u> </u> |           |            |            |
|----------|--------|----------|-----------|------------|------------|
| Device M | arking | Device   | Reel Size | Tape width | Quantity   |
| FDS44    | l65    | FDS4465  | 13"       | 12mm       | 2500 units |

| Symbol                                      | Parameter   | Test Conditions   | Min  | Тур                      | Max                     | Units |
|---|---|---|------|--------------------------|-------------------------|-------|
| Off Char                                    | acteristics                                       | 1   |      |                          |                         | I     |
| BV <sub>DSS</sub>                           | Drain-Source Breakdown Voltage                    | $V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$  | -20  |                          |                         | V     |
| <u>ΔBV<sub>DSS</sub></u><br>ΔT <sub>J</sub> | Breakdown Voltage Temperature Coefficient         | $I_D$ = -250 μA, Referenced to 25°C   |      | -12                      |                         | mV/°C |
| I <sub>DSS</sub>                            | Zero Gate Voltage Drain Current                   | $V_{DS} = -16 \text{ V},  V_{GS} = 0 \text{ V}$   |      |                          | -1                      | μΑ    |
| I <sub>GSSF</sub>                           | Gate-Body Leakage, Forward                        | $V_{GS} = 8 \text{ V}, \qquad V_{DS} = 0 \text{ V}$   |      |                          | 100                     | nA    |
| I <sub>GSSR</sub>                           | Gate-Body Leakage, Reverse                        | $V_{GS} = -8 \text{ V}, \qquad V_{DS} = 0 \text{ V}$  |      |                          | -100                    | nA    |
| On Char                                     | acteristics (Note 2)                              |   |      |                          |                         |       |
| V <sub>GS(th)</sub>                         | Gate Threshold Voltage                            | $V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$   | -0.4 | -0.6                     | -1.5                    | V     |
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$      | Gate Threshold Voltage<br>Temperature Coefficient | $I_D = -250 \mu\text{A}$ , Referenced to 25°C   |      | 3                        |                         | mV/°C |
| R <sub>DS(on)</sub>                         | Static Drain–Source<br>On–Resistance              | $\begin{split} V_{GS} = -4.5 \text{ V}, & I_D = -13.5 \text{ A} \\ V_{GS} = -2.5 \text{ V}, & I_D = -12 \text{ A} \\ V_{GS} = -1.8 \text{ V}, & I_D = -10.5 \text{ A} \\ V_{GS} = -4.5 \text{ V}, I_D = -13.5 \text{A}, T_J = 125 ^{\circ}\text{C} \end{split}$ |      | 6.7<br>8.0<br>9.8<br>9.0 | 8.5<br>10.5<br>14<br>13 | mΩ    |
| I <sub>D(on)</sub>                          | On–State Drain Current                            | $V_{GS} = -4.5 \text{ V}, \qquad V_{DS} = -5 \text{ V}$   | -50  |                          |                         | Α     |
| <b>g</b> <sub>FS</sub>                      | Forward Transconductance                          | $V_{DS} = -5 \text{ V}, \qquad I_{D} = -13.5 \text{ A}$   |      | 70                       |                         | S     |
| Dynamic                                     | Characteristics                                   |   |      | •                        |                         |       |
| C <sub>iss</sub>                            | Input Capacitance                                 | $V_{DS} = -10 \text{ V}, \qquad V_{GS} = 0 \text{ V},$  |      | 8237                     |                         | pF    |
| Coss  | Output Capacitance                                | f = 1.0 MHz   |      | 1497                     |                         | pF    |
| C <sub>rss</sub>                            | Reverse Transfer Capacitance                      | 7   |      | 750                      |                         | pF    |
| R <sub>g</sub>                              | Gate Resistance                                   |   | 0.1  | 3.0                      | 6.0                     | Ω     |
| Switchir                                    | g Characteristics (Note 2)                        |   |      |                          |                         |       |
| t <sub>d(on)</sub>                          | Turn-On Delay Time                                | $V_{DD} = -10V$ , $I_{D} = -1 A$ ,  |      | 20                       | 36                      | ns    |
| t <sub>r</sub>                              | Turn-On Rise Time                                 | $V_{GS} = -4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$  |      | 24                       | 38                      | ns    |
| t <sub>d(off)</sub>                         | Turn-Off Delay Time                               | 1   |      | 300                      | 480                     | ns    |
| t <sub>f</sub>                              | Turn-Off Fall Time                                |   |      | 140                      | 224                     | ns    |
| Qg  | Total Gate Charge                                 | $V_{DS} = -10 \text{ V}, \qquad I_{D} = -13.5 \text{ A}, \\ V_{GS} = -4.5 \text{ V}$  |      | 86                       | 120                     | nC    |
| Q <sub>gs</sub>                             | Gate-Source Charge                                |   |      | 20                       |                         | nC    |
| $Q_{gd}$                                    | Gate-Drain Charge                                 |   |      | 11                       |                         | nC    |
| Drain-S                                     | ource Diode Characteristics                       | and Maximum Ratings   |      |                          |                         |       |
| Is  | Maximum Continuous Drain-Source                   |   |      |                          | -2.1                    | Α     |
| V <sub>SD</sub>                             | Drain–Source Diode Forward<br>Voltage             | $V_{GS} = 0 \text{ V},  I_{S} = -2.1 \text{ A}  \text{(Note 2)}$  |      | -0.6                     | -1.2                    | V     |

1. R<sub>BUA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a) 50 °C/W when mounted on a 1in² pad of 2 oz copper



b) 105 °C/W when mounted on a .04 in<sup>2</sup> pad of 2 oz copper



c) 125 °C/W when mounted on a minimum pad.

Scale 1:1 on letter size paper

**2.** Pulse Test: Pulse Width <  $300\mu s$ , Duty Cycle < 2.0%

# **Typical Characteristics**

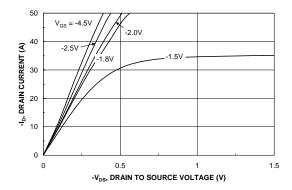


Figure 1. On-Region Characteristics.

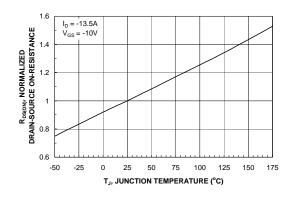


Figure 3. On-Resistance Variation with Temperature.

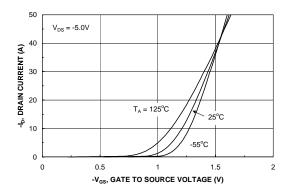


Figure 5. Transfer Characteristics.

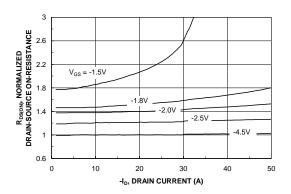


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

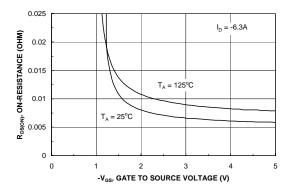


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

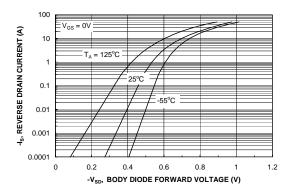
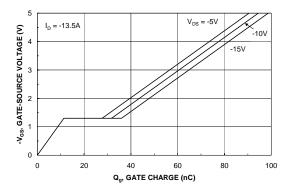


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

## **Typical Characteristics**



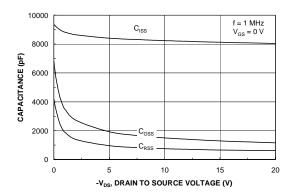


Figure 7. Gate Charge Characteristics.

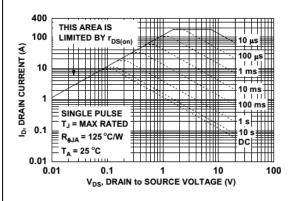


Figure 8. Capacitance Characteristics.

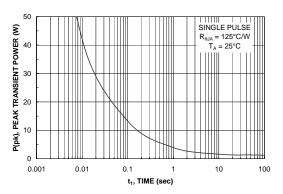


Figure 9. Maximum Safe Operating Area.



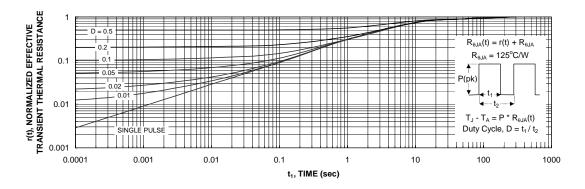


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient thermal response will change depending on the circuit board design.



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